

Hybrid

SINGLE PASS PASSIVE AND DIE PLACEMENT



Lowest cost of ownership, Highest first pass yield
Ultimate applications flexibility, Die attach at passives speeds

Main benefits:

- **Scalable throughput**
 - Passive placement speed up to **121,000 CPH** (IPC9850)
 - Flipchip bonding up to **27,000 CPH**
- **Accuracy**
 - **7 micron** for FC / Dies
 - **15 micron** for Passives
- **Cost of Ownership**
 - **Minimal** maintenance **cost**
 - **Lowest** energy **consumption**
 - Passive and Die placement in one pass
- **Scalable Technology**
 - **100 %** Active placement force control
 - Defect rates lower than **1 DPM**
 - Tape, tray, waffle, wafer feeding, dip fluxing
 - Full Die traceability (SECS/GEM, CAMX)
- **Industry 4.0 ready**
 - IPC-Hermes-9852
 - IPC-CFX
 - SECS/GEM
 - CAMX

SPECIFICATIONS

	Hybrid 3	Hybrid 5
Maximum output per hour	99k cph	165k cph
Maximum output IPC9850/IPC9850A	79k cph	121k cph
Placement accuracy @ Cpk>1	15 µm for Passives 7 µm for Flip Chips / Dies	15 µm for Passives 7 µm for Flip Chips / Dies
Min. component size	0.25 x 0.125 mm (008004, 0201M)	0.25 x 0.125 mm (008004, 0201M)
Max. component size	45 x 45 mm (1.77 x 1.77")	45 x 45 mm (1.77 x 1.77")
Max. component height	10.5 mm (taller on request)	10.5 mm (taller on request)
Programmable placement force (in steps of 0.1 N)	0.5 - 8 N	0.5 - 8 N
Min. board size:	50 x 50 mm (2 x 2") (50 x 25 mm (2 x 1") on request)	50 x 50 mm (2 x 2") (50 x 25 mm (2 x 1") on request)
Max. board size: - Standard - Optional board width - Optional board length	475 x 390 mm (18.7 x 15.35") 543 mm (21.37") 800 mm (31.5")	515 x 390 mm (20.28 x 15.35") 543 mm (21.37") 1500 mm (59.05")
Transport directions	Left to Right Right to Left	Left to Right Right to Left
Board thickness	0.3 to 6 mm (10 mm on request)	0.3 to 6 mm (10 mm on request)
Max. tape feeding lanes (8 mm) - SF feeders	126	210
Feeding options	Tape, waffle pack, stick, tray, wafer, others	Tape, waffle pack, stick, tray, wafer, others
OPEN MES data interfaces	CAMX & SECS/GEMS, IPC-HERMES, IPC-CFX	CAMX & SECS/GEMS, IPC-HERMES, IPC-CFX
Footprint (L x W) (incl. SF trolleys)	2,760 x 2,187 mm	3,720 x 2,187 mm

Please contact your sales representative for a quotation.
Actual amount of reachable feeder slots may vary based on machine configurations.

For more information, contact your local authorized K&S sales representative or visit www.kns.com

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